

DESCRIPTION

A-6165 is a soluble, proprietary additive that on addition to a conductive adhesive formulation can significantly decrease the volume resistivity of the cured material.

HIGHLIGHTS

- Improves electrical conductivity in metal filled conductive paste formulations
- Soluble in most resin systems
- May improve the thermal conductivity in some formulations

TYPICAL PHYSICAL AND CHEMICAL PROPERTIES

PROPERTY	METHOD	RESULT
Appearance at Room Temperature	Visual	Dark brown viscous liquid
Flash Point	Closed Cup	> 175°C
Recommended Storage Temp		+5°C or colder

Data is for reference only and may vary depending on testing method used.

RECOMMENDED FORMULATION USE:

A-6165 is recommended for use as an additive in combination with metal fillers (e.g. silver or Ag coated Cu) to further decrease volume resistivity in electrically conductive adhesive compositions. The recommended addition level of the A-6165 to a metal-filled adhesive formulation is less than or equal to about 1% by weight of the formulation's total resin content. Higher levels of the A-6165 can degrade the adhesion of the composition and do not necessarily further reduce volume resistivity. Addition of less than about 0.5% of by weight A-6165 to the resin base will not yield optimum electrical performance. The best electrical results are obtained when the resin system attains a gel point at or slightly above 160°C. Lower cure temperatures are usually insufficient to activate the A-6165.

CONTACT:

REQUEST A SAMPLE OR PLACE AN ORDER

Customer Support

☎ 858-348-1122

✉ support@designermoleculesinc.com

REF: DMI Part Number: A6165